

#	Layer	Thickness	Description	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts
	Top Surface Finish	0.006mm		
1	Top Side	0.030mm	Starting foil 1/4oz. after plating and processing	
		0.065mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
2	Inner Layer 1	0.030mm	Starting foil 1/4oz. after plating and processing	
		0.065mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
3	Inner Layer 2	0.035mm	ED Base Copper	
		0.150mm	Core IPC-4101/127/128	FR-4.1 filled, halogen free
4	Inner Layer 3	0.035mm	ED Base Copper	
		0.125mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
5	Inner Layer 4	0.035mm	ED Base Copper	
		0.150mm	Core IPC-4101/127/128	FR-4.1 filled, halogen free
6	Inner Layer 5	0.035mm	ED Base Copper	
		0.125mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
7	Inner Layer 6	0.035mm	ED Base Copper	
		0.150mm	Core IPC-4101/127/128	FR-4.1 filled, halogen free
8	Inner Layer 7	0.035mm	ED Base Copper	
		0.125mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
9	Inner Layer 8	0.035mm	ED Base Copper	
		0.150mm	Core IPC-4101/127/128	FR-4.1 filled, halogen free
10	Inner Layer 9	0.035mm	ED Base Copper	
		0.065mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
11	Inner Layer 10	0.030mm	Starting foil 1/4oz. after plating and processing	
		0.065mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
12	Bottom Side	0.030mm	Starting foil 1/4oz. after plating and processing	
	Bottom Surface Finish	0.006mm		
	Bottom Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts
Total thickness: 1.676mm				

notes:

Final copper thicknesses according to IPC-6012 **HDI12_2-8-2_167_35_2V13**

Standard: Surface Finish ENIG
(Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm)

Please follow our sectional design rules:
▶ www.we-online.com/designruleshdi_en

PCB Thickness Tolerance: ± 10%			
customer		created	
pcb name		approved	
engineer		format	A4, landscape
date			

For impedance matching stackups: Please consult our specialists: HDI@we-online.com

Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen

